

In re Patent Application of:
MAGNI ET AL.
Serial No. 10/036,335
Filing Date: DECEMBER 26, 2001

In the Specification:

Please replace the paragraph beginning at page 1, line 9, with the following rewritten paragraph:

It is well known that semiconductor electronic devices comprising pressure sensors and optical sensors have become more important and are more frequently used. To access the active portion of the electronic devices, ~~the portion~~ that comprises the sensor, it is necessary to form packages that include a window.

Please replace the paragraph beginning at page 1, line 16, with the following rewritten paragraph:

FIG. 1 shows a prospective perspective view of a package 1 for an electronic device with a sensor formed according to a first known method. Beginning from a substrate 2, for example, made from semiconductor material, dies made from semiconductor material are formed and comprise an electronic circuit 3. Such dies are encapsulated by a package 4 made from plastic material, which leaves a portion of the electronic circuit 3 uncovered. For example, an overmolding technique is used to form the package 4 such that a liquid epoxy resin 5 is dispensed on the substrate 2 and on the perimeter of the electronic circuit portion that must remain uncovered.

Please replace the paragraph beginning at page 5, line 14, with the following rewritten paragraph:

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FIG. 1 shows a schematic ~~prospective~~ perspective view of a protective package for an electronic device according to the prior art;

Please replace the paragraph beginning at page 6, line 31, with the following rewritten paragraph:

According to the invention, the upper half-mold ~~12~~ 15 has an insert or lug which is formed from an element 17 made out of a material that can be elastically deformed, abutting in pressing contact against the electronic circuit 13. In a preferred embodiment, the upper half-mold ~~12~~ 15 has a cavity 16 that is substantially defined by the half-mold ~~12~~ 15 and by the element 17 made out of a material that can be elastically deformed. Advantageously, the element 17 is an elastic membrane. The membrane 17 is preferably made out of an elastomer.

Please replace the paragraph beginning at page 8, line 4, with the following rewritten paragraph:

As it has already been disclosed in the prior art, a pressure is exerted onto the two half-molds such that they are clamped together when the material for forming the protective package is injected, according to the invention. When the upper half-mold ~~12~~ 15 is fastened to the lower half-mold 11, the membrane 17 is not in contact with the integrated circuit 13. According to the invention, the cavity 16 of the mold 10 defined by the membrane 17, is filled with a pressure fluid at a predetermined value. The fluid pressure is then regulated

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at a suitable value.